



# PMEG6045ETP-Q

High-temperature 60 V, 4.5 A Schottky barrier rectifier

20 February 2023

Product data sheet

## 1. General description

Planar Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD128 small and flat lead Surface-Mounted Device (SMD) plastic package.

## 2. Features and benefits

- Average forward current:  $I_{F(AV)} \leq 4.5$  A
- Reverse voltage:  $V_R \leq 60$  V
- Low forward voltage
- High power capability due to clip-bonding technology
- Small and flat lead SMD plastic package
- High temperature  $T_j \leq 175$  °C
- Suitable for both reflow and wave soldering
- Qualified according to AEC-Q101 and recommended for use in automotive applications

## 3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Reverse polarity protection
- Low power consumption application



## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $f = 20$ kHz; square wave; $T_{sp} \leq 155$ °C	-	-	4.5	A
$V_R$	reverse voltage	$T_j = 25$ °C	-	-	60	V
$V_F$	forward voltage	$I_F = 4.5$ A; $t_p \leq 300$ $\mu$ s; $\delta \leq 0.02$ ; $T_j = 25$ °C; pulsed	-	460	530	mV
$I_R$	reverse current	$V_R = 60$ V; $T_j = 25$ °C; pulsed	-	115	400	$\mu$ A

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	 CFP5 (SOD128)	 sym001
2	A	anode		

[1] The marking bar indicates the cathode.

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
<a href="#">PMEG6045ETP-Q</a>	CFP5	plastic, surface mounted package; 2 terminals; 4 mm pitch; 3.8 mm x 2.6 mm x 1 mm body	<a href="#">SOD128</a>

## 7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG6045ETP-Q	DC

## 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_R$	reverse voltage	$T_j = 25\text{ °C}$		-	60	V
$I_F$	forward current	$T_{sp} = 150\text{ °C}$		-	6.3	A
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $f = 20\text{ kHz}$ ; square wave; $T_{amb} \leq 35\text{ °C}$	[1]	-	4.5	A
		$\delta = 0.5$ ; $f = 20\text{ kHz}$ ; square wave; $T_{sp} \leq 155\text{ °C}$		-	4.5	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 8.3\text{ ms}$ ; half-sine wave; $T_{j(init)} = 25\text{ °C}$		-	70	A
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[2]	-	750	mW
			[3]	-	1250	mW
			[1]	-	2500	mW
$T_j$	junction temperature			-	175	°C
$T_{amb}$	ambient temperature			-55	175	°C
$T_{stg}$	storage temperature			-65	175	°C

[1] Device mounted on a ceramic Printed-Circuit Board (PCB),  $Al_2O_3$ , standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode  $1\text{ cm}^2$ .

## 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	200	K/W
			[1] [3]	-	-	120	K/W
			[1] [4]	-	-	60	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[5]	-	-	12	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- [4] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.
- [5] Soldering point of cathode tab.

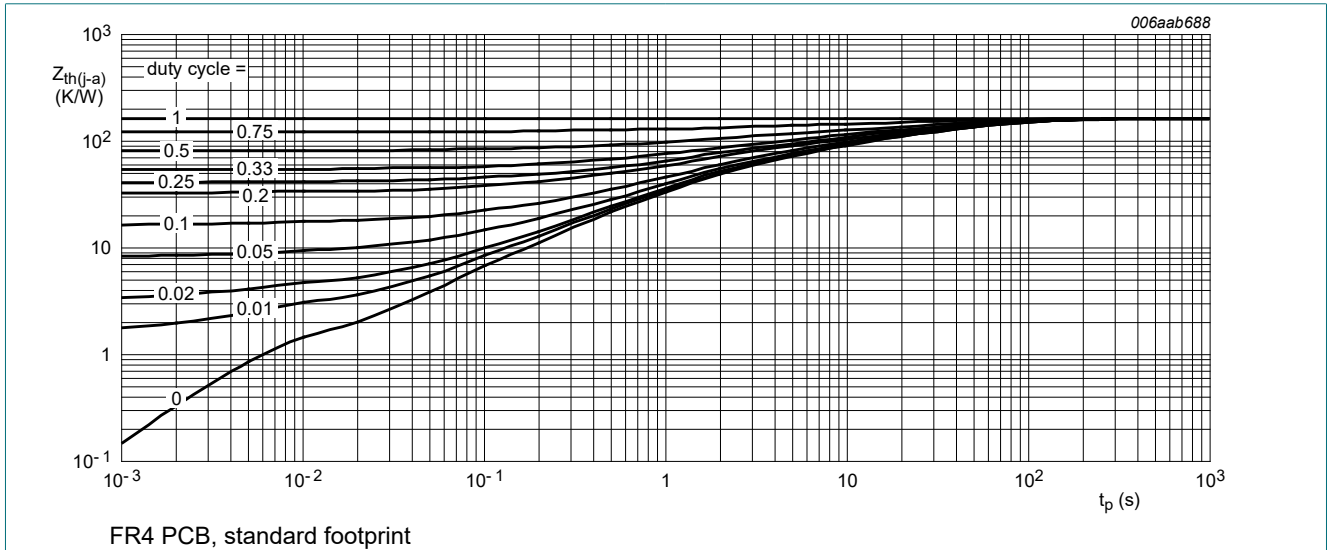


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

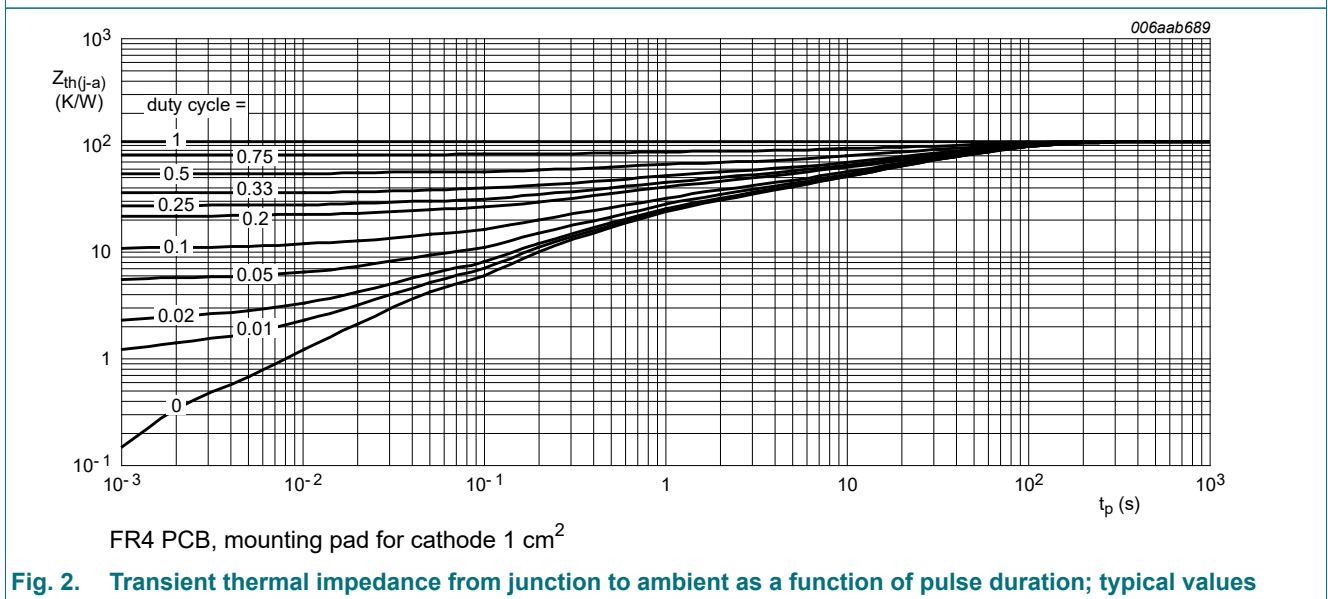
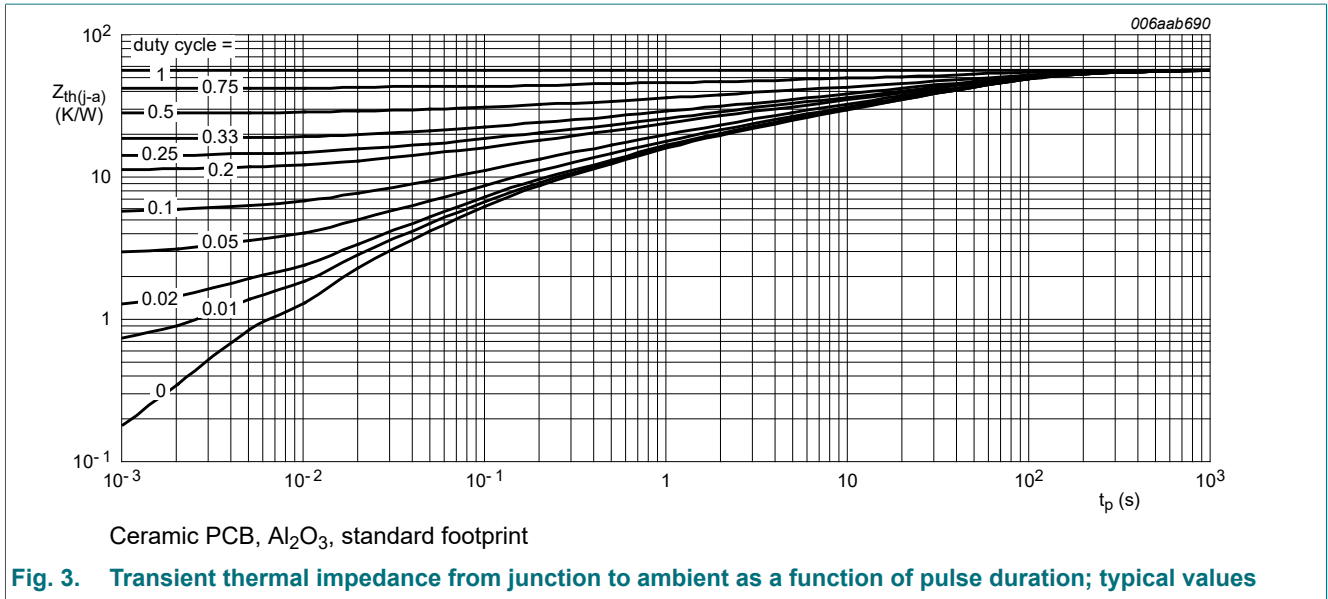


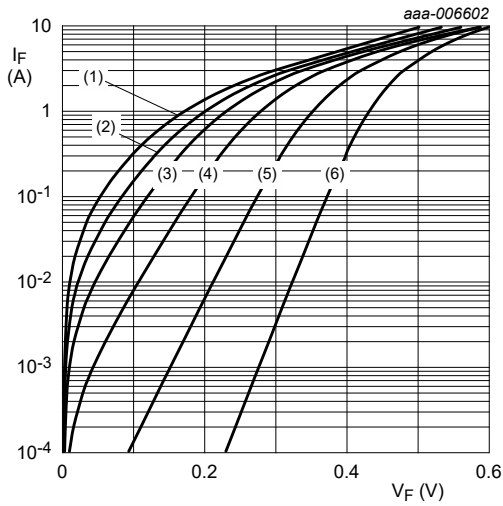
Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



## 10. Characteristics

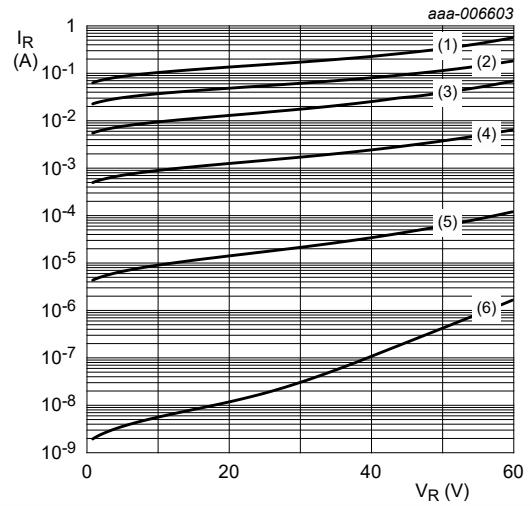
Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 0.1 A; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>j</sub> = 25 °C; pulsed	-	275	310	mV
		I <sub>F</sub> = 0.5 A; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>j</sub> = 25 °C; pulsed	-	325	-	mV
		I <sub>F</sub> = 1 A; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>j</sub> = 25 °C; pulsed	-	355	400	mV
		I <sub>F</sub> = 1.5 A; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>j</sub> = 25 °C; pulsed	-	375	-	mV
		I <sub>F</sub> = 2 A; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>j</sub> = 25 °C; pulsed	-	390	440	mV
		I <sub>F</sub> = 3 A; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>j</sub> = 25 °C; pulsed	-	420	475	mV
		I <sub>F</sub> = 4 A; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>j</sub> = 25 °C; pulsed	-	450	510	mV
		I <sub>F</sub> = 4.5 A; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>j</sub> = 25 °C; pulsed	-	460	530	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 5 V; T <sub>j</sub> = 25 °C; pulsed	-	7	20	μA
		V <sub>R</sub> = 10 V; T <sub>j</sub> = 25 °C; pulsed	-	9	40	μA
		V <sub>R</sub> = 30 V; T <sub>j</sub> = 25 °C; pulsed	-	20	80	μA
		V <sub>R</sub> = 60 V; T <sub>j</sub> = 25 °C; pulsed	-	115	400	μA
		V <sub>R</sub> = 10 V; T <sub>j</sub> = 125 °C; pulsed	-	9	-	mA
		V <sub>R</sub> = 60 V; T <sub>j</sub> = 125 °C; pulsed	-	70	300	mA
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 1 V; f = 1 MHz; T <sub>j</sub> = 25 °C	-	575	-	pF
		V <sub>R</sub> = 10 V; f = 1 MHz; T <sub>j</sub> = 25 °C	-	200	-	pF
t <sub>rr</sub>	reverse recovery time	I <sub>F</sub> = 0.5 A; I <sub>R</sub> = 0.5 A; I <sub>R(meas)</sub> = 0.1 A; T <sub>j</sub> = 25 °C	-	20	-	ns
V <sub>FRM</sub>	peak forward recovery voltage	I <sub>F</sub> = 1 A; dI <sub>F</sub> /dt = 40 A/μs; T <sub>j</sub> = 25 °C	-	385	-	mV



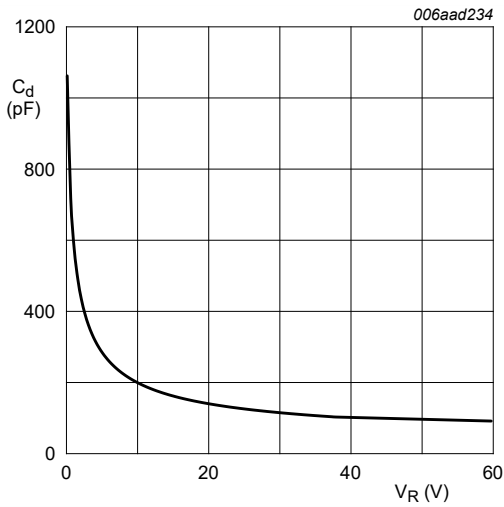
pulsed condition  
 (1)  $T_j = 175\text{ °C}$   
 (2)  $T_j = 150\text{ °C}$   
 (3)  $T_j = 125\text{ °C}$   
 (4)  $T_j = 85\text{ °C}$   
 (5)  $T_j = 25\text{ °C}$   
 (6)  $T_j = -40\text{ °C}$

**Fig. 4. Forward current as a function of forward voltage; typical values**



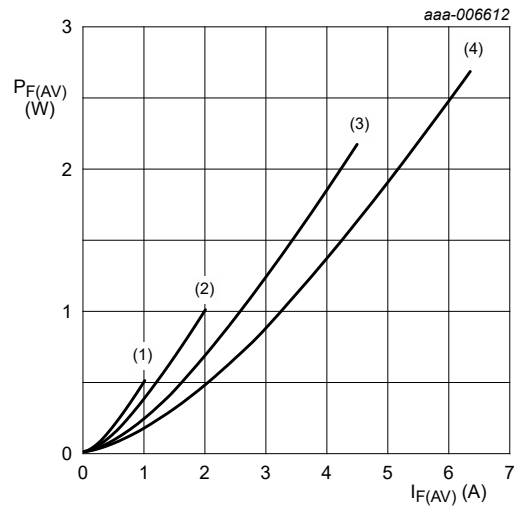
pulsed condition  
 (1)  $T_j = 175\text{ °C}$   
 (2)  $T_j = 150\text{ °C}$   
 (3)  $T_j = 125\text{ °C}$   
 (4)  $T_j = 85\text{ °C}$   
 (5)  $T_j = 25\text{ °C}$   
 (6)  $T_j = -40\text{ °C}$

**Fig. 5. Reverse current as a function of reverse voltage; typical values**



$f = 1\text{ MHz}; T_{amb} = 25\text{ °C}$

**Fig. 6. Diode capacitance as a function of reverse voltage; typical values**



$T_j = 175\text{ °C}$   
 (1)  $\delta = 0.1$   
 (2)  $\delta = 0.2$   
 (3)  $\delta = 0.5$   
 (4)  $\delta = 1$

**Fig. 7. Average forward power dissipation as a function of average forward current; typical values**

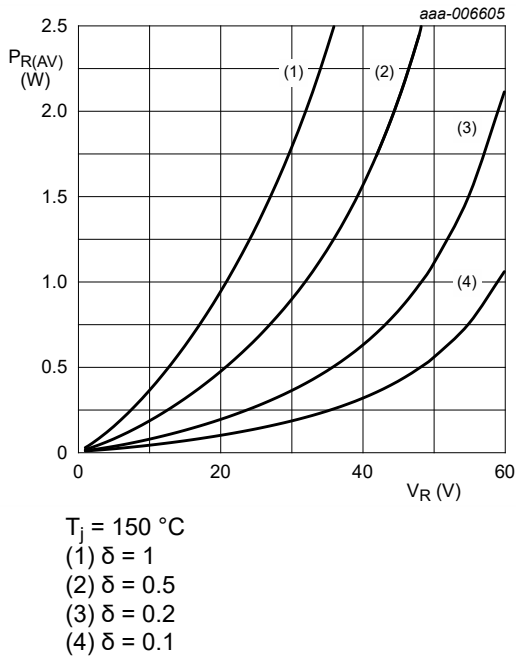


Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values

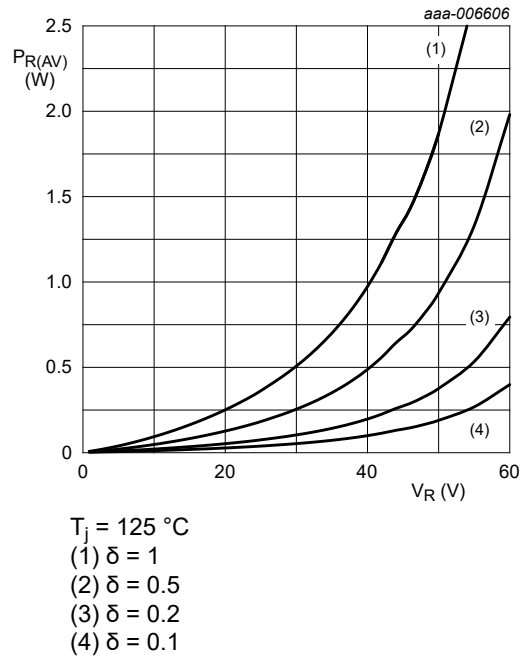


Fig. 9. Average reverse power dissipation as a function of reverse voltage; typical values

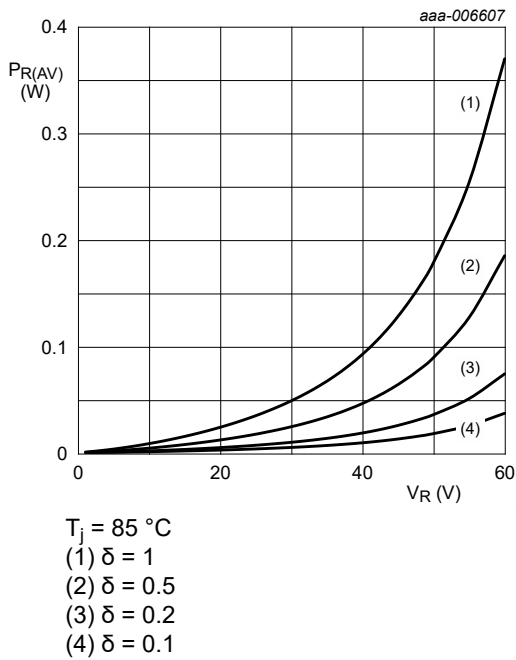


Fig. 10. Average reverse power dissipation as a function of reverse voltage; typical values

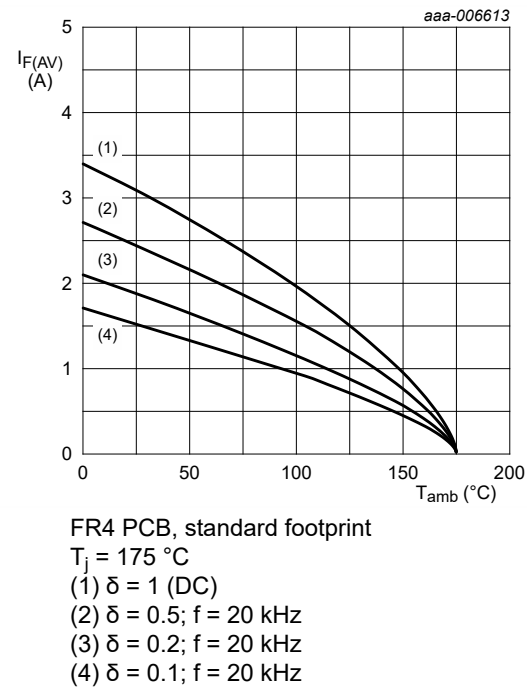
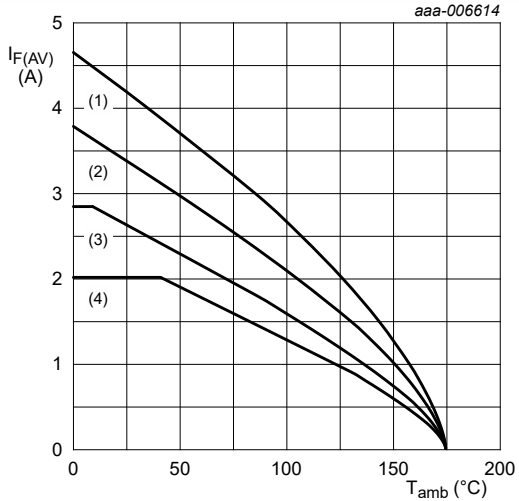
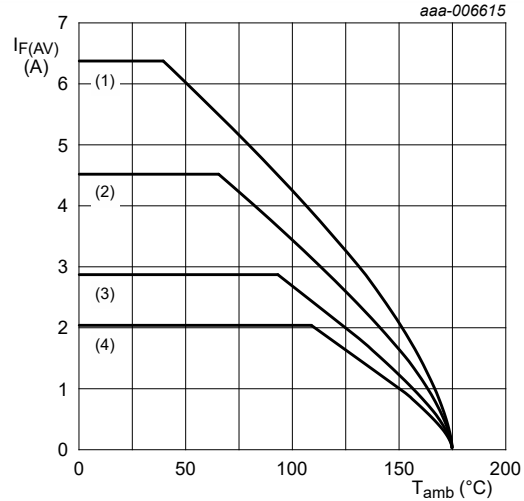


Fig. 11. Average forward current as a function of ambient temperature; typical values



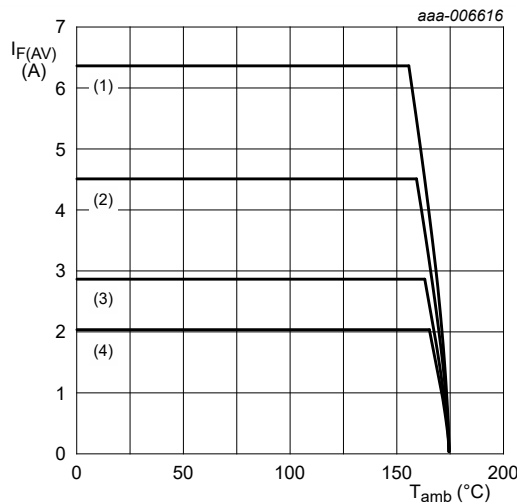
FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>  
 $T_j = 175\text{ °C}$   
 (1)  $\delta = 1$  (DC)  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig. 12. Average forward current as a function of ambient temperature; typical values**



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint  
 $T_j = 175\text{ °C}$   
 (1)  $\delta = 1$  (DC)  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig. 13. Average forward current as a function of ambient temperature; typical values**



$T_j = 175\text{ °C}$   
 (1)  $\delta = 1$  (DC)  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig. 14. Average forward current as a function of solder point temperature; typical values**

### 11. Test information

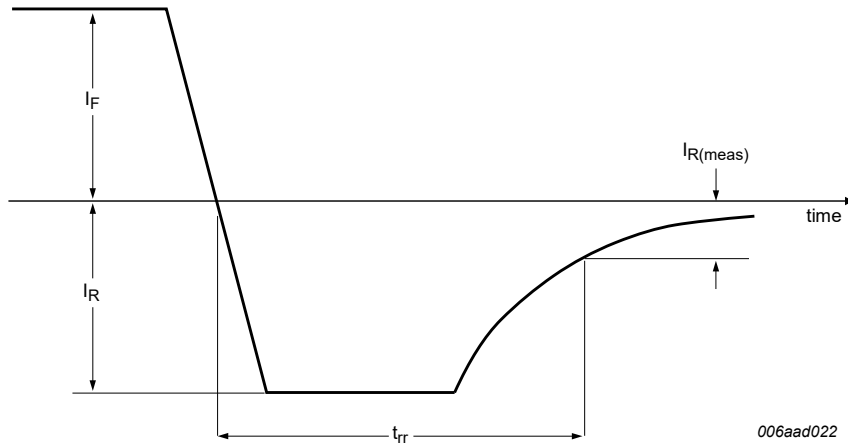


Fig. 15. Reverse recovery definition

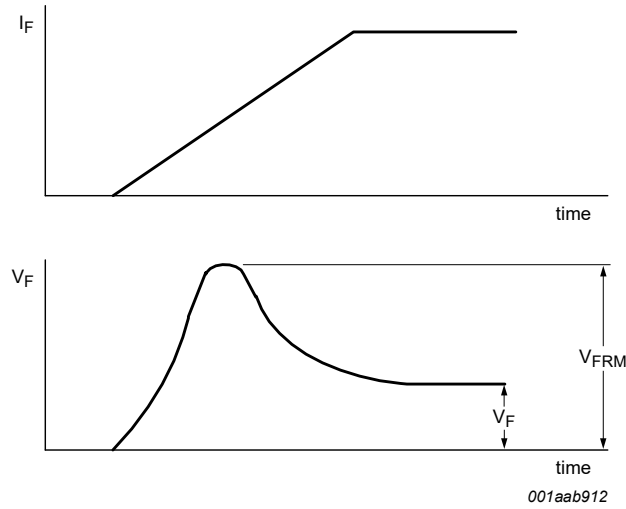


Fig. 16. Forward recovery definition

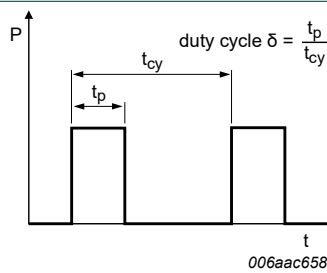


Fig. 17. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:

$$I_{F(AV)} = I_M \times \delta \text{ with } I_M \text{ defined as peak current,}$$

$$I_{RMS} = I_{F(AV)} \text{ at DC,}$$

$$I_{RMS} = I_M \times \sqrt{\delta} \text{ with } I_{RMS} \text{ defined as RMS current.}$$



**Quality information**

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

**12. Package outline**

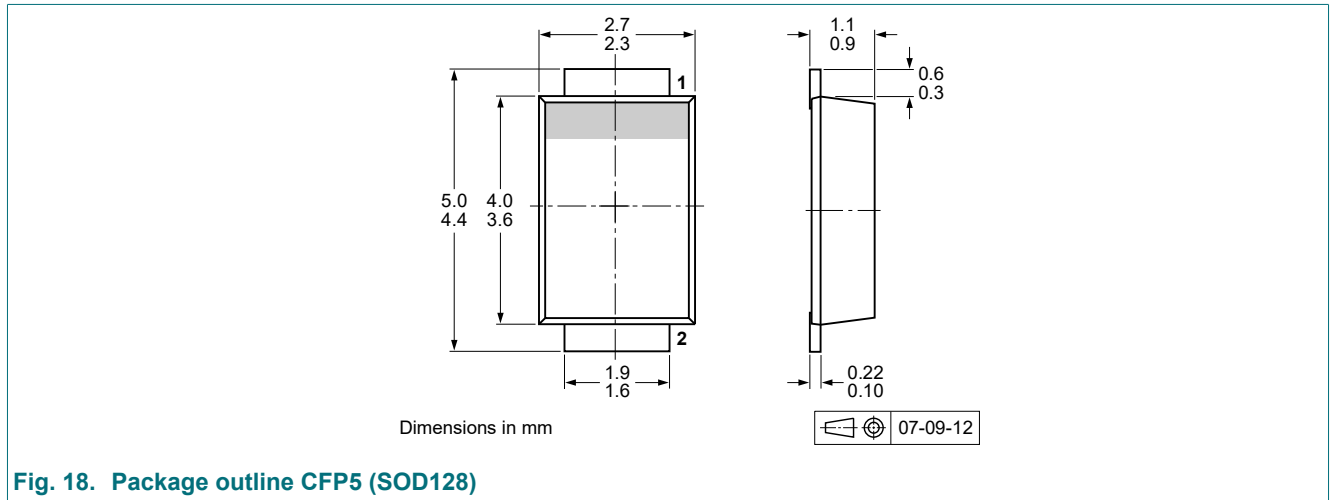


Fig. 18. Package outline CFP5 (SOD128)

**13. Soldering**

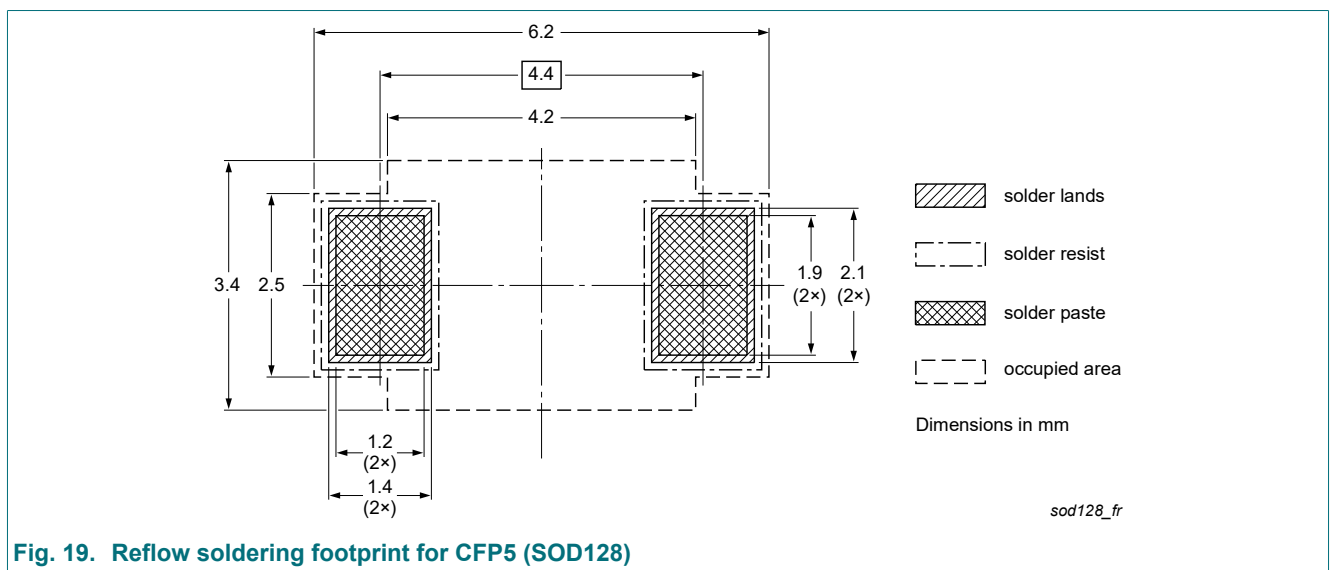
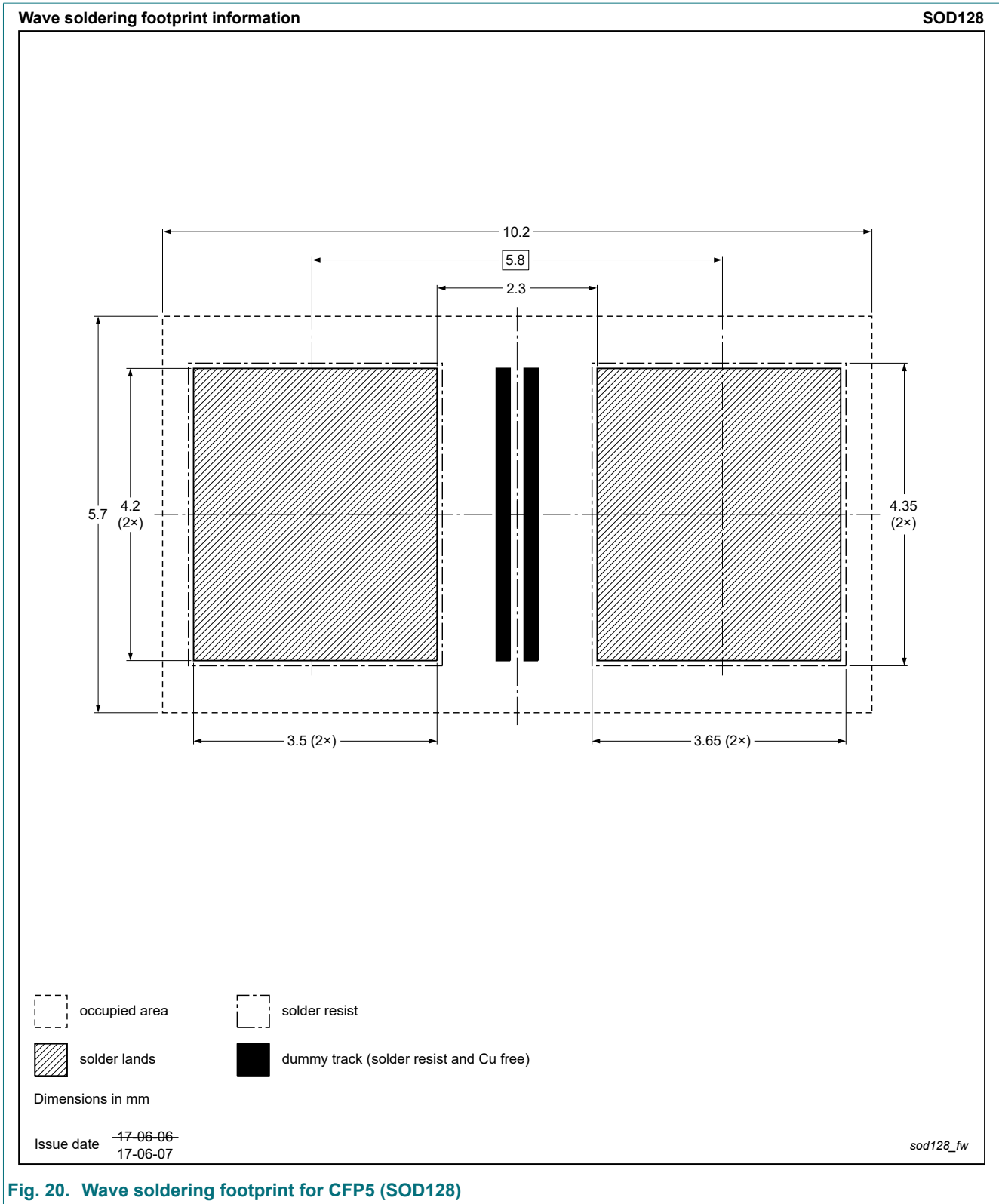


Fig. 19. Reflow soldering footprint for CFP5 (SOD128)



**Fig. 20. Wave soldering footprint for CFP5 (SOD128)**

## 14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG6045ETP-Q v.2	20230220	Product data sheet	-	PMEG6045ETP-Q v.1
Modifications:	<ul style="list-style-type: none"><li>Limiting values: Measurement conditions for <math>I_{FSM}</math> changed from square wave to half-sine wave.</li></ul>			
PMEG6045ETP-Q v.1	20210719	Product data sheet	-	-

## 15. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at <https://www.nexperia.com>.

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